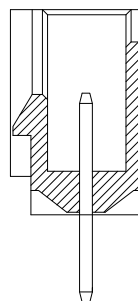
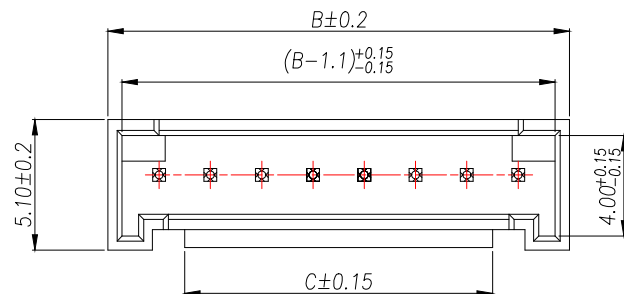
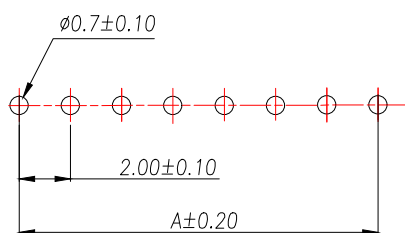
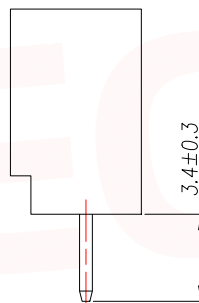
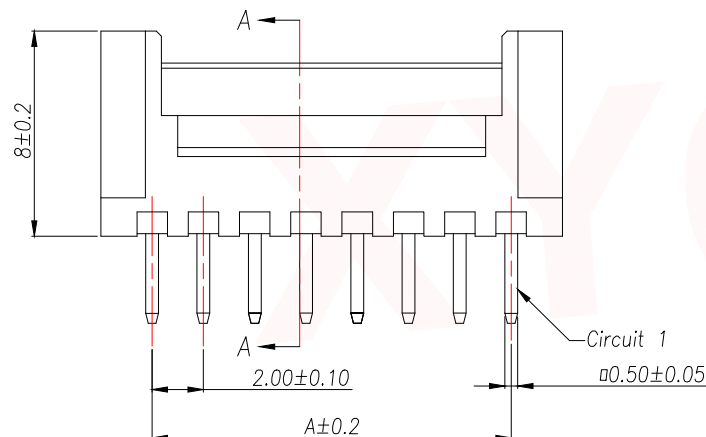


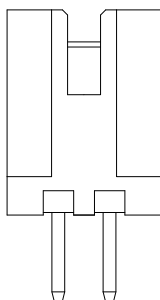
PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



2P外观

技术要求:

- 1、塑件材料:PA66
- 2、接触件:黄铜镀锡
- 3、接触电阻: $\leq 10m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压:250V AC DC
- 6、额定电流:2.0A AC DC
- 7、耐压:能承受1000V AC/Minute
- 8、工作温度: $-25^{\circ}\sim +85^{\circ}$
- 9、可焊性试验:浸锡面积 $\geq 95\%$ 温度 220^{+5}_{-0} , 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B	C
XY-HY2.0-2A11	2	2	6	
XY-HY2.0-3A11	3	4	8	2
XY-HY2.0-4A11	4	6	10	4
XY-HY2.0-5A11	5	8	12	6
XY-HY2.0-6A11	6	10	14	8
XY-HY2.0-7A11	7	12	16	10
XY-HY2.0-8A11	8	14	18	12
XY-HY2.0-9A11	9	16	20	14
XY-HY2.0-10A11	10	18	22	16
XY-HY2.0-11A11	11	20	24	18
XY-HY2.0-12A11	12	22	26	20
XY-HY2.0-13A11	13	24	28	22
XY-HY2.0-14A11	14	26	30	24
XY-HY2.0-15A11	15	28	32	26

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*± 5°	APR. Alex	TITLE: WAFER 2.0mm H8.0mm 180° DIP		
.XX±0.25	.X*± 3°	CHK. Jack	DWG NO. XY-HY2.0-NA11		
.XXX±0.15	.XX*± 1°	DRA. Can	PROJ. 		CUSTOMER DRAWING
			SIZE A4	SCALE 1:1	SHEET 1/1